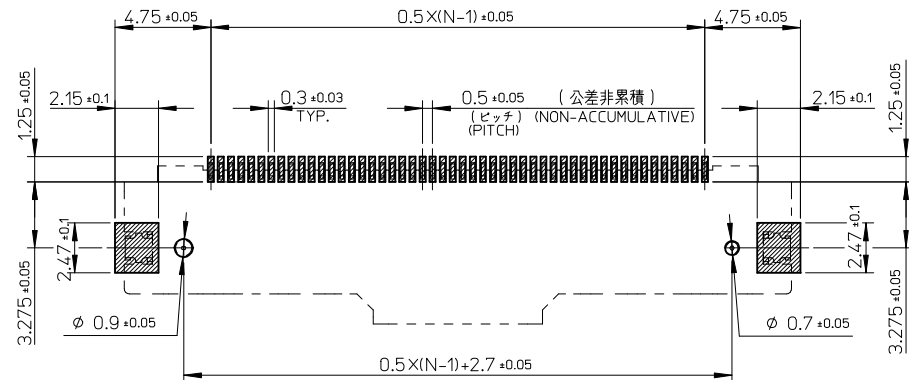
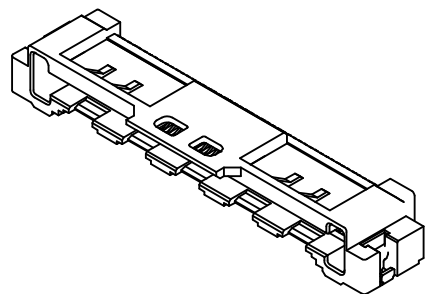
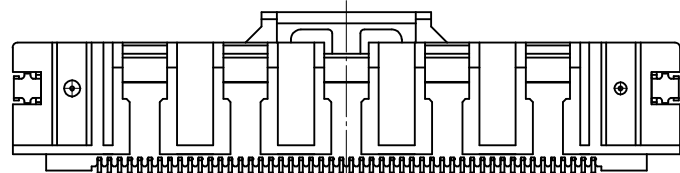
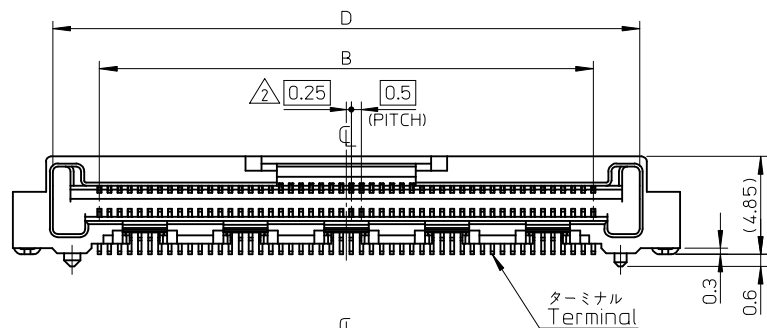
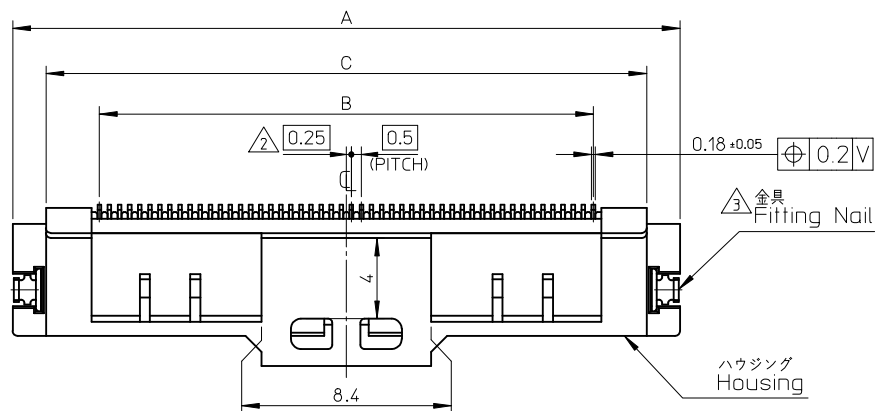
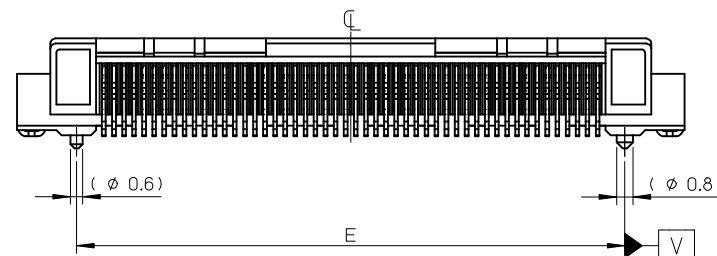
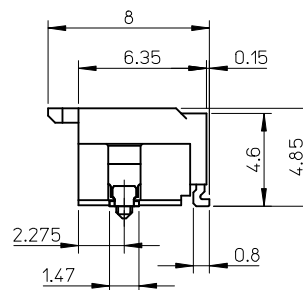


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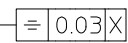
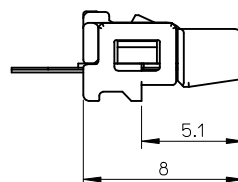
参考基板レイアウト
P.C BOARD PATTERN
DIMENSION (REF.)
(マウント面)
(MOUNTING SIDE)



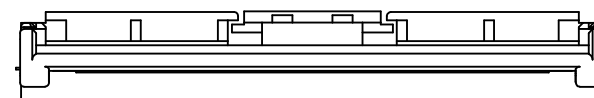
17.2	19.1	19.8	14.5	23.1	501864-3092	30
E	D	C	B	A	EMBOSSD TAPE PKG. ORDER No. オーダー番号	極数 CIRCUIT

CONNECTOR SERIES No. 501786-xx41

REVISED EC NO: A	DESCRIPTION DRWN: N. I. SHI CHKD: M. MATSUURA APPR: K. MORIKAWA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE //	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	M. TAKASAKI	08/12/05	TITLE 0.5 FFC TO BOARD CONN REC. HSG ASSY(RA)				
		10 OVER 30 UNDER	± 0.25	M. HAYASHI	08/12/05					
		30 OVER	± 0.3	N. UKITA	08/12/05	MOLEX MOLEX INCORPORATED				
		ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-501864-012		1 OF 2		
	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



適合FFC寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 接点部0.3±0.03)
(THICKNESS :CONTACT AREA 0.3±0.03)



・使用材料
MATERIAL
ハウジング
HOUSING

ターミナル
TERMINAL
メッキ
PLATIN

CONTACT AREA	ニッケル下地 金メッキ
GOLD OVER NICKEL PLATING	
SOLDER TAIL AREA	ニッケル下地 金メッキ
GOLD OVER NICKEL PLATING	

金具 : 銅合金 (t=0.25)
FITTING NAIL ニッケル下地 錫メッキ
COPPER ALLOY(t=0.25)
TIN OVER NICKEL PLATING.

△₂ N=偶数に適用 (N:極数)
APPLY FOR N=EVEN(IN:CIRCUIT)

△₃ パターン剥離止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B PATER.N.

△4 適合ジャケット:501783-**09
製品詳細寸法はSD-501783-004を参照下さい。
APPLICABLE JACKET:501783-**09.RE DETAILED DIMENSION,SEE SD-501783-004.

△5 適合ジャケットカバー:501784-**09
製品詳細寸法はSD-501784-004を参照下さい。
APPLICABLE JACKET:501784-**09.RE DETAILED DIMENSION,SEE SD-501784-004.

tb_frame_A3_J_AM_S
Rev. D 2004/06/28

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F

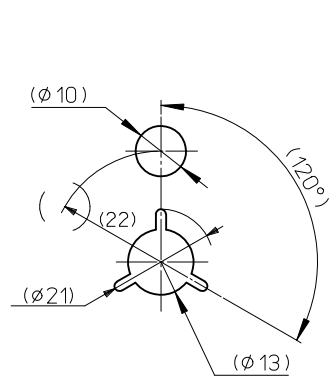
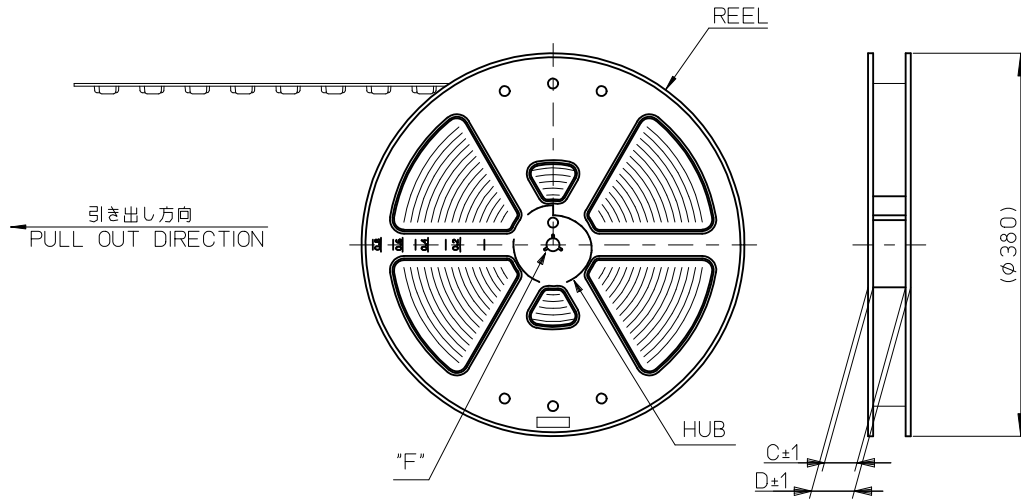
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D

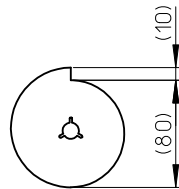
C

B

A



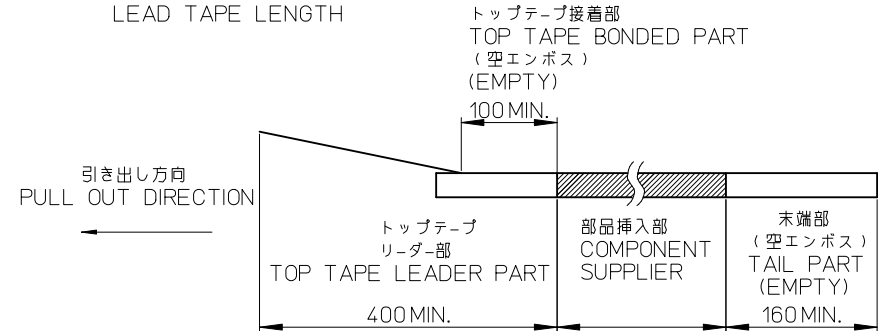
DETAIL "F"



HUB

NOTES

- 梱包数量：900 個ノリール
NUMBER OF CONNECTORS:900 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- 製品詳細寸法については図面 SD-501864-012を参照下さい。
RE DETAILED DIMENSION, SEE SD-501864-012.
- 材料(MATERIAL)
キャリアテープ(CARRIER TAPE)：ポリスチレン(POLYSTYRENE)
トップテープ(TOP TAPE)：PET, OTHER
リール(REEL)：ポリスチレン(POLYSTYRENE)

501864-**-92 MODEL NO.

REVISED	EC NO.: J2012-0899 DWG: KAGUMO CHKD: KAGAHASHI APPR: KORIYAKAWA	2012/01/18 2012/01/18 2012/01/19	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
				10 UNDER ±0.2		DRAWN BY DATE M. TAKASAKI 08/12/05		TITLE EMBSTP PKG FOR 0.5 FFC TO BOARD CONN RA TYPE -LEAD FREE-			
				10 OVER 30 UNDER ±0.25		CHECKED BY DATE M. HAYASHI 08/12/05					
				30 OVER ±0.3		APPROVED BY DATE N. UKITA 08/12/05		MOLEX INCORPORATED			
				ANGULAR ±1 °		MATERIAL NO. 501864-**-92					
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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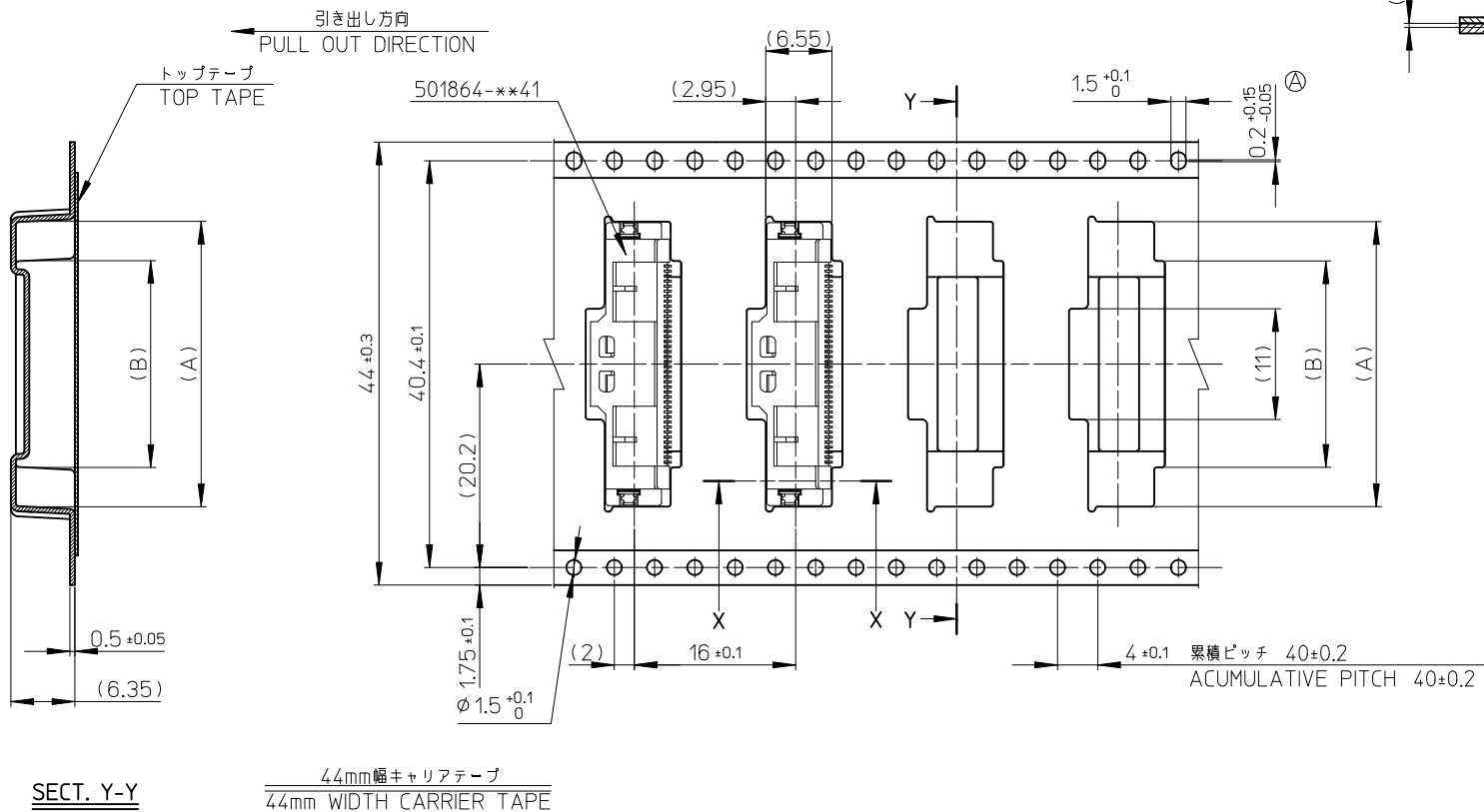
6

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2



44	49.4	45.4	15.5	23.3	501864-3092	30
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	製品番号 MATERIAL NO.	極数 CKT

SEE SHEET 1 OF 2 EC NO.: J2012-0899 DRWN:KNAGUMO 2012/01/18 CHKD:KTAHASHI 2012/01/18 APPR:KMORIKAWA 2012/01/19 A	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		10 UNDER	±0.2	DRAWN BY M. TAKASAKI	DATE 08/12/05	TITLE EMBSTP PKG FOR 0.5 FFC TO BOARD CONN RA TYPE -LEAD FREE- MOLEX INCORPORATED					
		10 OVER 30 UNDER	±0.25	CHECKED BY M. HAYASHI	DATE 08/12/05						
		30 OVER	±0.3	APPROVED BY N. UKITA	DATE 08/12/05						
		ANGULAR ±1 °		MATERIAL NO. 501864-**-92		DOCUMENT NO. SD-501864-013		SHEET NO. 2 OF 2			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							
				SIZE A3							